Lattice Semiconductor Corporation - LC4256V-5FTN256BC Datasheet

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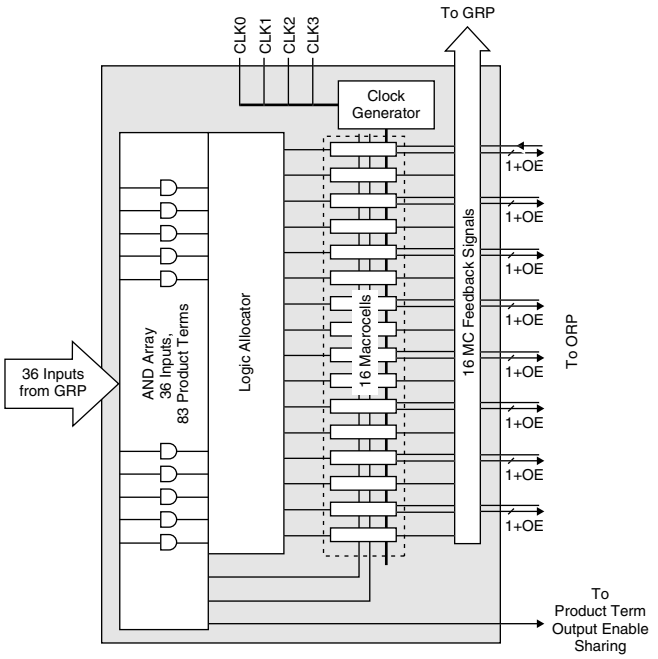
Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	160
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-5ftn256bc

Figure 2. Generic Logic Block



AND Array

The programmable AND Array consists of 36 inputs and 83 output product terms. The 36 inputs from the GRP are used to form 72 lines in the AND Array (true and complement of the inputs). Each line in the array can be connected to any of the 83 output product terms via a wired-AND. Each of the 80 logic product terms feed the logic allocator with the remaining three control product terms feeding the Shared PT Clock, Shared PT Initialization and Shared PT OE. The Shared PT Clock and Shared PT Initialization signals can optionally be inverted before being fed to the macrocells.

Every set of five product terms from the 80 logic product terms forms a product term cluster starting with PT0. There is one product term cluster for every macrocell in the GLB. Figure 3 is a graphical representation of the AND Array.

Table 5. Product Term Expansion Capability

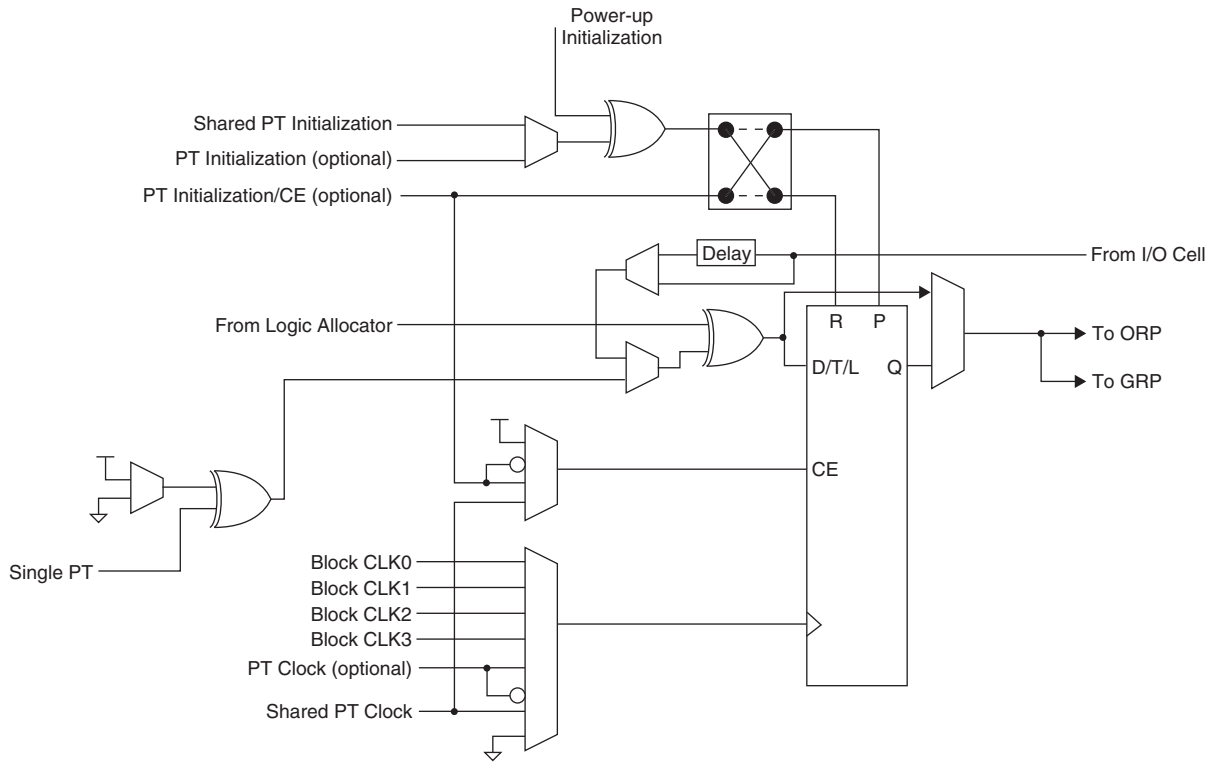
Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/ Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP}. When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

Macrocell

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

Figure 5. Macrocell



Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

- Block CLK2
- Block CLK3
- PT Clock
- PT Clock Inverted
- Shared PT Clock
- Ground

Clock Enable Multiplexer

Each macrocell has a 4:1 clock enable multiplexer. This allows the clock enable signal to be selected from the following four sources:

- PT Initialization/CE
- PT Initialization/CE Inverted
- Shared PT Clock
- Logic High

Initialization Control

The ispMACH 4000 family architecture accommodates both block-level and macrocell-level set and reset capability. There is one block-level initialization term that is distributed to all macrocell registers in a GLB. At the macrocell level, two product terms can be “stolen” from the cluster associated with a macrocell to be used for set/reset functionality. A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility.

Note that the reset/preset swapping selection feature affects power-up reset as well. All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the block-level initialization, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the block-level initialization or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

GLB Clock Generator

Each ispMACH 4000 device has up to four clock pins that are also routed to the GRP to be used as inputs. These pins drive a clock generator in each GLB, as shown in Figure 6. The clock generator provides four clock signals that can be used anywhere in the GLB. These four GLB clock signals can consist of a number of combinations of the true and complement edges of the global clock signals.

Figure 6. GLB Clock Generator

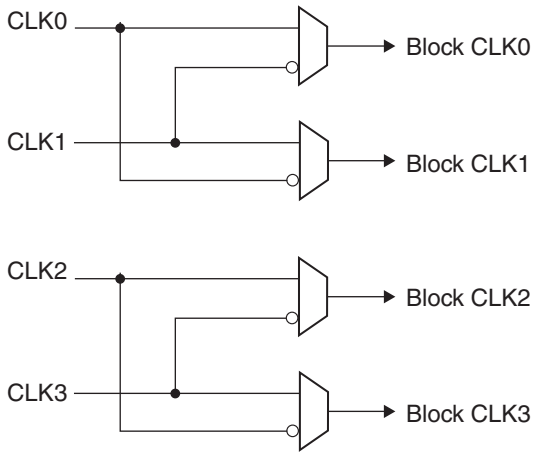
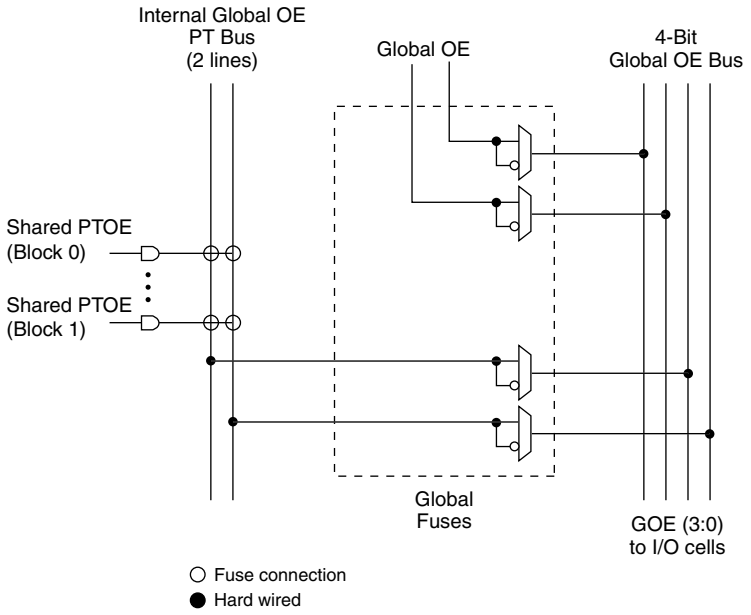


Figure 10. Global OE Generation for ispMACH 4032



Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E^2 low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

I/O Recommended Operating Conditions

Standard	V_{CCO} (V)[1]	
	Min.	Max.
LVTTL	3.0	3.6
LVCMOS 3.3	3.0	3.6
Extended LVCMOS 3.3[2]	2.7	3.6
LVCMOS 2.5	2.3	2.7
LVCMOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for V_{CCO} are the average of the min. and max. values.
2. ispMACH 4000Z only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 4]	Input Leakage Current (ispMACH 4000Z)	$0 \le V_{IN} < V_{CCO}$	—	0.5	1	µA
I_{IH}[1]	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \le 5.5V$	—	—	10	µA
I_{IL}, I_{IH}[1]	Input Leakage Current (ispMACH 4000V/B/C)	$0 \le V_{IN} \le 3.6V$, $T_j = 105°C$	—	—	10	µA
		$0 \le V_{IN} \le 3.6V$, $T_j = 130°C$	—	—	15	µA
I_{IH}[1,2]	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \le 5.5V$, $T_j = 105°C$ $3.0V \le V_{CCO} \le 3.6V$	—	—	20	µA
		$3.6V < V_{IN} \le 5.5V$, $T_j = 130°C$ $3.0V \le V_{CCO} \le 3.6V$	—	—	50	µA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \le V_{IN} \le 0.7V_{CCO}$	-30	—	-150	µA
	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \le V_{IN} \le 0.7V_{CCO}$	-30	—	-200	µA
I_{PD}	I/O Weak Pull-down Resistor Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MIN)	30	—	150	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7\ V_{CCO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0V \le V_{IN} \le V_{BHT}$	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive Current	$V_{BHT} \le V_{IN} \le V_{CCO}$	—	—	-150	µA
V_{BHT}	Bus Hold Trip Points	—	V_{CCO} * 0.35	—	V_{CCO} * 0.65	V
C_1	I/O Capacitance[3]	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V$, $V_{IO} = 0$ to V_{IH} (MAX)	—		—	
C_2	Clock Capacitance[3]	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V$, $V_{IO} = 0$ to V_{IH} (MAX)	—		—	
C_3	Global Input Capacitance[3]	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V$, $V_{IO} = 0$ to V_{IH} (MAX)	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. 5V tolerant inputs and I/O should only be placed in banks where $3.0V \le V_{CCO} \le 3.6V$.
3. $T_A = 25°C$, f = 1.0MHz
4. I_{IH} excursions of up to 1.5µA maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

Supply Current, ispMACH 4000Z (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4256ZC						
ICC[1, 2, 3, 5]	Operating Power Supply Current	Vcc = 1.8V, T_A = 25°C	—	341	—	µA
		Vcc = 1.9V, T_A = 70°C	—	361	—	µA
		Vcc = 1.9V, T_A = 85°C	—	372	—	µA
		Vcc = 1.9V, T_A = 125°C	—	468	—	µA
ICC[4, 5]	Standby Power Supply Current	Vcc = 1.8V, T_A = 25°C	—	13	—	µA
		Vcc = 1.9V, T_A = 70°C	—	32	55	µA
		Vcc = 1.9V, T_A = 85°C	—	43	90	µA
		Vcc = 1.9V, T_A = 125°C	—	135	—	µA

1. T_A = 25°C, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. V_{CCO} = 3.6V, V_{IN} = 0V or $V_{CCO,}$ bus maintenance turned off. V_{IN} above V_{CCO} will add transient current above the specified standby I_{CC}.
5. Includes V_{CCO} current without output loading.

ispMACH 4000Z External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description[1, 2, 3]	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
t_{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
t_S	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
t_{ST}	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
t_{SIR}	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
t_{SIRZ}	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
t_H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t_{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
t_{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
t_R	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
t_{RW}	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
$t_{PTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
$t_{GPTOE/DIS}$	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
t_{CW}	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
t_{WIR}	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
f_{MAX}[4]	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
f_{MAX} (Ext.)	clock frequency with external feedback, $[1 / (t_S + t_{CO})]$	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

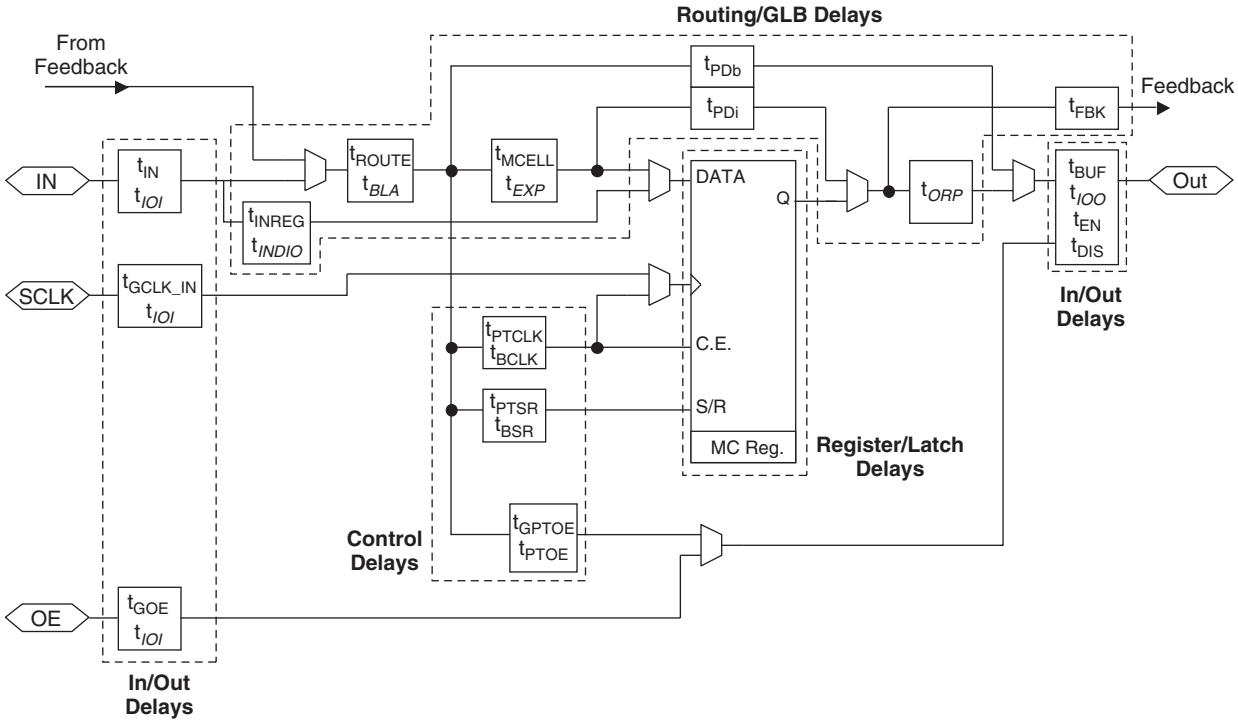
Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.

Timing Model

The task of determining the timing through the ispMACH 4000 family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, refer to TN1004, ispMACH 4000 Timing Model Design and Usage Guidelines.

Figure 11. ispMACH 4000 Timing Model



Note: Italicized items are optional delay adders.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
t_{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	0.28	—	ns
t_{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	1.67	—	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	1.12	—	1.12	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	—	0.87	ns
t_{BSR}	Block PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.11	—	1.41	—	1.51	—	1.61	ns
t_{GPTOE}	Global PT OE Delay	—	2.83	—	4.13	—	5.33	—	5.33	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.83	—	2.13	—	2.33	—	2.83	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000V/B/C Timing Adders[1] (Cont.)

Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t_{INDIO}	t_{INREG}	Input register delay	—	1.00	—	1.00	—	1.00	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters									
LVTTL_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters									
LVTTL_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing. Timing v.3.2

1. Refer to TN1004, ispMACH 4000 Timing Model Design and Usage Guidelines for information regarding use of these adders.

ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections: 44-Pin TQFP

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections: 100-Pin TQFP

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-	GND	-
2	-	TDI	-	TDI	-	TDI	-
3	0	A8	A^8	B0	B^0	C12	C^3
4	0	A9	A^9	B2	B^1	C10	C^2
5	0	A10	A^10	B4	B^2	C6	C^1
6	0	A11	A^11	B6	B^3	C2	C^0
7	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
8	0	A12	A^12	B8	B^4	D12	D^3
9	0	A13	A^13	B10	B^5	D10	D^2
10	0	A14	A^14	B12	B^6	D6	D^1
11	0	A15	A^15	B13	B^7	D4	D^0
12*	0	I	-	I	-	I	-
13	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
14	0	B15	B^15	C14	C^7	E4	E^0
15	0	B14	B^14	C12	C^6	E6	E^1
16	0	B13	B^13	C10	C^5	E10	E^2
17	0	B12	B^12	C8	C^4	E12	E^3
18	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
19	0	B11	B^11	C6	C^3	F2	F^0
20	0	B10	B^10	C5	C^2	F6	F^1
21	0	B9	B^9	C4	C^1	F10	F^2
22	0	B8	B^8	C2	C^0	F12	F^3
23*	0	I	-	I	-	I	-
24	-	TCK	-	TCK	-	TCK	-
25	-	VCC	-	VCC	-	VCC	-
26	-	GND	-	GND	-	GND	-
27*	0	I	-	I	-	I	-
28	0	B7	B^7	D13	D^7	G12	G^3
29	0	B6	B^6	D12	D^6	G10	G^2
30	0	B5	B^5	D10	D^5	G6	G^1
31	0	B4	B^4	D8	D^4	G2	G^0
32	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
33	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
34	0	B3	B^3	D6	D^3	H12	H^3
35	0	B2	B^2	D4	D^2	H10	H^2
36	0	B1	B^1	D2	D^1	H6	H^1
37	0	B0	B^0	D0	D^0	H2	H^0
38	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
39	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
40	-	VCC	-	VCC	-	VCC	-
41	1	C0	C^0	E0	E^0	I2	I^0

Ordering Information

Note: ispMACH 4000 devices are all dual marked except the slowest commercial speed grade ispMACH 4000Z devices. For example, the commercial speed grade LC4128C-5T100C is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade ispMACH 4000Z devices are marked as commercial grade only.

Conventional Packaging

ispMACH 4000ZC (Zero Power, 1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35M56C	32	1.8	3.5	csBGA	56	32	C
	LC4032ZC-5M56C	32	1.8	5	csBGA	56	32	C
	LC4032ZC-75M56C	32	1.8	7.5	csBGA	56	32	C
	LC4032ZC-35T48C	32	1.8	3.5	TQFP	48	32	C
	LC4032ZC-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032ZC-75T48C	32	1.8	7.5	TQFP	48	32	C
LC4064ZC	LC4064ZC-37M132C	64	1.8	3.7	csBGA	132	64	C
	LC4064ZC-5M132C	64	1.8	5	csBGA	132	64	C
	LC4064ZC-75M132C	64	1.8	7.5	csBGA	132	64	C
	LC4064ZC-37T100C	64	1.8	3.7	TQFP	100	64	C
	LC4064ZC-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064ZC-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064ZC-37M56C	64	1.8	3.7	csBGA	56	32	C
	LC4064ZC-5M56C	64	1.8	5	csBGA	56	32	C
	LC4064ZC-75M56C	64	1.8	7.5	csBGA	56	32	C
	LC4064ZC-37T48C	64	1.8	3.7	TQFP	48	32	C
	LC4064ZC-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064ZC-75T48C	64	1.8	7.5	TQFP	48	32	C
LC4128ZC	LC4128ZC-42M132C	128	1.8	4.2	csBGA	132	96	C
	LC4128ZC-75M132C	128	1.8	7.5	csBGA	132	96	C
	LC4128ZC-42T100C	128	1.8	4.2	TQFP	100	64	C
	LC4128ZC-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256ZC	LC4256ZC-45T176C	256	1.8	4.5	TQFP	176	128	C
	LC4256ZC-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256ZC-45M132C	256	1.8	4.5	csBGA	132	96	C
	LC4256ZC-75M132C	256	1.8	7.5	csBGA	132	96	C
	LC4256ZC-45T100C	256	1.8	4.5	TQFP	100	64	C
	LC4256ZC-75T100C	256	1.8	7.5	TQFP	100	64	C

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices

Device	Part Number	Macrocells	Voltage	tPD	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5M56I	32	1.8	5	csBGA	56	32	I
	LC4032ZC-75M56I	32	1.8	7.5	csBGA	56	32	I
	LC4032ZC-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032ZC-75T48I	32	1.8	7.5	TQFP	48	32	I

ispMACH 4000B (2.5V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256B	LC4256B-3FT256AC	256	2.5	3	ftBGA	256	128	C
	LC4256B-5FT256AC	256	2.5	5	ftBGA	256	128	C
	LC4256B-75FT256AC	256	2.5	7.5	ftBGA	256	128	C
	LC4256B-3FT256BC	256	2.5	3	ftBGA	256	160	C
	LC4256B-5FT256BC	256	2.5	5	ftBGA	256	160	C
	LC4256B-75FT256BC	256	2.5	7.5	ftBGA	256	160	C
	LC4256B-3F256AC[1]	256	2.5	3	fpBGA	256	128	C
	LC4256B-5F256AC[1]	256	2.5	5	fpBGA	256	128	C
	LC4256B-75F256AC[1]	256	2.5	7.5	fpBGA	256	128	C
	LC4256B-3F256BC[1]	256	2.5	3	fpBGA	256	160	C
	LC4256B-5F256BC[1]	256	2.5	5	fpBGA	256	160	C
	LC4256B-75F256BC[1]	256	2.5	7.5	fpBGA	256	160	C
	LC4256B-3T176C	256	2.5	3	TQFP	176	128	C
	LC4256B-5T176C	256	2.5	5	TQFP	176	128	C
	LC4256B-75T176C	256	2.5	7.5	TQFP	176	128	C
	LC4256B-3T100C	256	2.5	3	TQFP	100	64	C
	LC4256B-5T100C	256	2.5	5	TQFP	100	64	C
	LC4256B-75T100C	256	2.5	7.5	TQFP	100	64	C
LC4384B	LC4384B-35FT256C	384	2.5	3.5	ftBGA	256	192	C
	LC4384B-5FT256C	384	2.5	5	ftBGA	256	192	C
	LC4384B-75FT256C	384	2.5	7.5	ftBGA	256	192	C
	LC4384B-35F256C[1]	384	2.5	3.5	fpBGA	256	192	C
	LC4384B-5F256C[1]	384	2.5	5	fpBGA	256	192	C
	LC4384B-75F256C[1]	384	2.5	7.5	fpBGA	256	192	C
	LC4384B-35T176C	384	2.5	3.5	TQFP	176	128	C
	LC4384B-5T176C	384	2.5	5	TQFP	176	128	C
	LC4384B-75T176C	384	2.5	7.5	TQFP	176	128	C
LC4512B	LC4512B-35FT256C	512	2.5	3.5	ftBGA	256	208	C
	LC4512B-5FT256C	512	2.5	5	ftBGA	256	208	C
	LC4512B-75FT256C	512	2.5	7.5	ftBGA	256	208	C
	LC4512B-35F256C[1]	512	2.5	3.5	fpBGA	256	208	C
	LC4512B-5F256C[1]	512	2.5	5	fpBGA	256	208	C
	LC4512B-75F256C[1]	512	2.5	7.5	fpBGA	256	208	C
	LC4512B-35T176C	512	2.5	3.5	TQFP	176	128	C
	LC4512B-5T176C	512	2.5	5	TQFP	176	128	C
	LC4512B-75T176C	512	2.5	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC[1]	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC[1]	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC[1]	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC[1]	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC[1]	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC[1]	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
	LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C[1]	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C[1]	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C[1]	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000V (3.3V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FT256AI	256	3.3	5	ftBGA	256	128	I
	LC4256V-75FT256AI	256	3.3	7.5	ftBGA	256	128	I
	LC4256V-10FT256AI	256	3.3	10	ftBGA	256	128	I
	LC4256V-5FT256BI	256	3.3	5	ftBGA	256	160	I
	LC4256V-75FT256BI	256	3.3	7.5	ftBGA	256	160	I
	LC4256V-10FT256BI	256	3.3	10	ftBGA	256	160	I
	LC4256V-5F256AI[1]	256	3.3	5	fpBGA	256	128	I
	LC4256V-75F256AI[1]	256	3.3	7.5	fpBGA	256	128	I
	LC4256V-10F256AI[1]	256	3.3	10	fpBGA	256	128	I
	LC4256V-5F256BI[1]	256	3.3	5	fpBGA	256	160	I
	LC4256V-75F256BI[1]	256	3.3	7.5	fpBGA	256	160	I
	LC4256V-10F256BI[1]	256	3.3	10	fpBGA	256	160	I
	LC4256V-5T176I	256	3.3	5	TQFP	176	128	I
	LC4256V-75T176I	256	3.3	7.5	TQFP	176	128	I
	LC4256V-10T176I	256	3.3	10	TQFP	176	128	I
	LC4256V-5T144I	256	3.3	5	TQFP	144	96	I
	LC4256V-75T144I	256	3.3	7.5	TQFP	144	96	I
	LC4256V-10T144I	256	3.3	10	TQFP	144	96	I
	LC4256V-5T100I	256	3.3	5	TQFP	100	64	I
	LC4256V-75T100I	256	3.3	7.5	TQFP	100	64	I
	LC4256V-10T100I	256	3.3	10	TQFP	100	64	I
LC4384V	LC4384V-5FT256I	384	3.3	5	ftBGA	256	192	I
	LC4384V-75FT256I	384	3.3	7.5	ftBGA	256	192	I
	LC4384V-10FT256I	384	3.3	10	ftBGA	256	192	I
	LC4384V-5F256I[1]	384	3.3	5	fpBGA	256	192	I
	LC4384V-75F256I[1]	384	3.3	7.5	fpBGA	256	192	I
	LC4384V-10F256I[1]	384	3.3	10	fpBGA	256	192	I
	LC4384V-5T176I	384	3.3	5	TQFP	176	128	I
	LC4384V-75T176I	384	3.3	7.5	TQFP	176	128	I
	LC4384V-10T176I	384	3.3	10	TQFP	176	128	I
LC4512V	LC4512V-5FT256I	512	3.3	5	ftBGA	256	208	I
	LC4512V-75FT256I	512	3.3	7.5	ftBGA	256	208	I
	LC4512V-10FT256I	512	3.3	10	ftBGA	256	208	I
	LC4512V-5F256I[1]	512	3.3	5	fpBGA	256	208	I
	LC4512V-75F256I[1]	512	3.3	7.5	fpBGA	256	208	I
	LC4512V-10F256I[1]	512	3.3	10	fpBGA	256	208	I
	LC4512V-5T176I	512	3.3	5	TQFP	176	128	I
	LC4512V-75T176I	512	3.3	7.5	TQFP	176	128	I
	LC4512V-10T176I	512	3.3	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75T48E	32	3.3	7.5	TQFP	48	32	E
	LC4032V-75T44E	32	3.3	7.5	TQFP	44	30	E
LC4064V	LC4064V-75T100E	64	3.3	7.5	TQFP	100	64	E
	LC4064V-75T48E	64	3.3	7.5	TQFP	48	32	E
	LC4064V-75T44E	64	3.3	7.5	TQFP	44	30	E
LC4128V	LC4128V-75T144E	128	3.3	7.5	TQFP	144	96	E
	LC4128V-75T128E	128	3.3	7.5	TQFP	128	92	E
	LC4128V-75T100E	128	3.3	7.5	TQFP	100	64	E
LC4256V	LC4256V-75T176E	256	3.3	7.5	TQFP	176	128	E
	LC4256V-75T144E	256	3.3	7.5	TQFP	144	96	E
	LC4256V-75T100E	256	3.3	7.5	TQFP	100	64	E

ispMACH 4000C (1.8V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064C	LC4064C-25TN100C	64	1.8	2.5	Lead-free TQFP	100	64	C
	LC4064C-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064C-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064C-25TN48C	64	1.8	2.5	Lead-free TQFP	48	32	C
	LC4064C-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064C-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
	LC4064C-25TN44C	64	1.8	2.5	Lead-free TQFP	44	30	C
	LC4064C-5TN44C	64	1.8	5	Lead-free TQFP	44	30	C
	LC4064C-75TN44C	64	1.8	7.5	Lead-free TQFP	44	30	C
LC4128C	LC4128C-27TN128C	128	1.8	2.7	Lead-free TQFP	128	92	C
	LC4128C-5TN128C	128	1.8	5	Lead-free TQFP	128	92	C
	LC4128C-75TN128C	128	1.8	7.5	Lead-free TQFP	128	92	C
	LC4128C-27TN100C	128	1.8	2.7	Lead-free TQFP	100	64	C
	LC4128C-5TN100C	128	1.8	5	Lead-free TQFP	100	64	C
	LC4128C-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256C	LC4256C-3FTN256AC	256	1.8	3	Lead-free ftBGA	256	128	C
	LC4256C-5FTN256AC	256	1.8	5	Lead-free ftBGA	256	128	C
	LC4256C-75FTN256AC	256	1.8	7.5	Lead-free ftBGA	256	128	C
	LC4256C-3FTN256BC	256	1.8	3	Lead-free ftBGA	256	160	C
	LC4256C-5FTN256BC	256	1.8	5	Lead-free ftBGA	256	160	C
	LC4256C-75FTN256BC	256	1.8	7.5	Lead-free ftBGA	256	160	C
	LC4256C-3FN256AC[1]	256	1.8	3	Lead-free fpBGA	256	128	C
	LC4256C-5FN256AC[1]	256	1.8	5	Lead-free fpBGA	256	128	C
	LC4256C-75FN256AC[1]	256	1.8	7.5	Lead-free fpBGA	256	128	C
	LC4256C-3FN256BC[1]	256	1.8	3	Lead-free fpBGA	256	160	C
	LC4256C-5FN256BC[1]	256	1.8	5	Lead-free fpBGA	256	160	C
	LC4256C-75FN256BC[1]	256	1.8	7.5	Lead-free fpBGA	256	160	C
	LC4256C-3TN176C	256	1.8	3	Lead-free TQFP	176	128	C
	LC4256C-5TN176C	256	1.8	5	Lead-free TQFP	176	128	C
	LC4256C-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256C-3TN100C	256	1.8	3	Lead-free TQFP	100	64	C
	LC4256C-5TN100C	256	1.8	5	Lead-free TQFP	100	64	C
	LC4256C-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C
LC4384C	LC4384C-35FTN256C	384	1.8	3.5	Lead-free ftBGA	256	192	C
	LC4384C-5FTN256C	384	1.8	5	Lead-free ftBGA	256	192	C
	LC4384C-75FTN256C	384	1.8	7.5	Lead-free ftBGA	256	192	C
	LC4384C-35FN256C[1]	384	1.8	3.5	Lead-free fpBGA	256	192	C
	LC4384C-5FN256C[1]	384	1.8	5	Lead-free fpBGA	256	192	C
	LC4384C-75FN256C[1]	384	1.8	7.5	Lead-free fpBGA	256	192	C
	LC4384C-35TN176C	384	1.8	3.5	Lead-free TQFP	176	128	C
	LC4384C-5TN176C	384	1.8	5	Lead-free TQFP	176	128	C
	LC4384C-75TN176C	384	1.8	7.5	Lead-free TQFP	176	128	C

ispMACH 4000C (1.8V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512C	LC4512C-35FTN256C	512	1.8	3.5	Lead-free ftBGA	256	208	C
	LC4512C-5FTN256C	512	1.8	5	Lead-free ftBGA	256	208	C
	LC4512C-75FTN256C	512	1.8	7.5	Lead-free ftBGA	256	208	C
	LC4512C-35FN256C[1]	512	1.8	3.5	Lead-free fpBGA	256	208	C
	LC4512C-5FN256C[1]	512	1.8	5	Lead-free fpBGA	256	208	C
	LC4512C-75FN256C[1]	512	1.8	7.5	Lead-free fpBGA	256	208	C
	LC4512C-35TN176C	512	1.8	3.5	Lead-free TQFP	176	128	C
	LC4512C-5TN176C	512	1.8	5	Lead-free TQFP	176	128	C
	LC4512C-75TN176C	512	1.8	7.5	Lead-free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000C (1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032C-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I
	LC4032C-10TN48I	32	1.8	10	Lead-free TQFP	48	32	I
	LC4032C-5TN44I	32	1.8	5	Lead-free TQFP	44	30	I
	LC4032C-75TN44I	32	1.8	7.5	Lead-free TQFP	44	30	I
	LC4032C-10TN44I	32	1.8	10	Lead-free TQFP	44	30	I
LC4064C	LC4064C-5TN100I	64	1.8	5	Lead-free TQFP	100	64	I
	LC4064C-75TN100I	64	1.8	7.5	Lead-free TQFP	100	64	I
	LC4064C-10TN100I	64	1.8	10	Lead-free TQFP	100	64	I
	LC4064C-5TN48I	64	1.8	5	Lead-free TQFP	48	32	I
	LC4064C-75TN48I	64	1.8	7.5	Lead-free TQFP	48	32	I
	LC4064C-10TN48I	64	1.8	10	Lead-free TQFP	48	32	I
	LC4064C-5TN44I	64	1.8	5	Lead-free TQFP	44	30	I
	LC4064C-75TN44I	64	1.8	5	Lead-free TQFP	44	30	I
	LC4064C-10TN44I	64	1.8	10	Lead-free TQFP	44	30	I
LC4128C	LC4128C-5TN128I	128	1.8	5	Lead-free TQFP	128	92	I
	LC4128C-75TN128I	128	1.8	7.5	Lead-free TQFP	128	92	I
	LC4128C-10TN128I	128	1.8	10	Lead-free TQFP	128	92	I
	LC4128C-5TN100I	128	1.8	5	Lead-free TQFP	100	64	I
	LC4128C-75TN100I	128	1.8	7.5	Lead-free TQFP	100	64	I
	LC4128C-10TN100I	128	1.8	10	Lead-free TQFP	100	64	I

ispMACH 4000V (3.3V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-3FTN256AC	256	3.3	3	Lead-free ftBGA	256	128	C
	LC4256V-5FTN256AC	256	3.3	5	Lead-free ftBGA	256	128	C
	LC4256V-75FTN256AC	256	3.3	7.5	Lead-free ftBGA	256	128	C
	LC4256V-3FTN256BC	256	3.3	3	Lead-free ftBGA	256	160	C
	LC4256V-5FTN256BC	256	3.3	5	Lead-free ftBGA	256	160	C
	LC4256V-75FTN256BC	256	3.3	7.5	Lead-free ftBGA	256	160	C
	LC4256V-3FN256AC[1]	256	3.3	3	Lead-free fpBGA	256	128	C
	LC4256V-5FN256AC[1]	256	3.3	5	Lead-free fpBGA	256	128	C
	LC4256V-75FN256AC[1]	256	3.3	7.5	Lead-free fpBGA	256	128	C
	LC4256V-3FN256BC[1]	256	3.3	3	Lead-free fpBGA	256	160	C
	LC4256V-5FN256BC[1]	256	3.3	5	Lead-free fpBGA	256	160	C
	LC4256V-75FN256BC[1]	256	3.3	7.5	Lead-free fpBGA	256	160	C
	LC4256V-3TN176C	256	3.3	3	Lead-free TQFP	176	128	C
	LC4256V-5TN176C	256	3.3	5	Lead-free TQFP	176	128	C
	LC4256V-75TN176C	256	3.3	7.5	Lead-free TQFP	176	128	C
	LC4256V-3TN144C	256	3.3	3	Lead-free TQFP	144	96	C
	LC4256V-5TN144C	256	3.3	5	Lead-free TQFP	144	96	C
	LC4256V-75TN144C	256	3.3	7.5	Lead-free TQFP	144	96	C
	LC4256V-3TN100C	256	3.3	3	Lead-free TQFP	100	64	C
	LC4256V-5TN100C	256	3.3	5	Lead-free TQFP	100	64	C
	LC4256V-75TN100C	256	3.3	7.5	Lead-free TQFP	100	64	C
LC4384V	LC4384V-35FTN256C	384	3.3	3.5	Lead-free ftBGA	256	192	C
	LC4384V-5FTN256C	384	3.3	5	Lead-free ftBGA	256	192	C
	LC4384V-75FTN256C	384	3.3	7.5	Lead-free ftBGA	256	192	C
	LC4384V-35FN256C[1]	384	3.3	3.5	Lead-free fpBGA	256	192	C
	LC4384V-5FN256C[1]	384	3.3	5	Lead-free fpBGA	256	192	C
	LC4384V-75FN256C[1]	384	3.3	7.5	Lead-free fpBGA	256	192	C
	LC4384V-35TN176C	384	3.3	3.5	Lead-free TQFP	176	128	C
	LC4384V-5TN176C	384	3.3	5	Lead-free TQFP	176	128	C
	LC4384V-75TN176C	384	3.3	7.5	Lead-free TQFP	176	128	C
LC4512V	LC4512V-35FTN256C	512	3.3	3.5	Lead-free ftBGA	256	208	C
	LC4512V-5FTN256C	512	3.3	5	Lead-free ftBGA	256	208	C
	LC4512V-75FTN256C	512	3.3	7.5	Lead-free ftBGA	256	208	C
	LC4512V-35FN256C[1]	512	3.3	3.5	Lead-free fpBGA	256	208	C
	LC4512V-5FN256C[1]	512	3.3	5	Lead-free fpBGA	256	208	C
	LC4512V-75FN256C[1]	512	3.3	7.5	Lead-free fpBGA	256	208	C
	LC4512V-35TN176C	512	3.3	3.5	Lead-free TQFP	176	128	C
	LC4512V-5TN176C	512	3.3	5	Lead-free TQFP	176	128	C
	LC4512V-75TN176C	512	3.3	7.5	Lead-free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.